

STK11C68 CMOS nvSRAM High Performance 8K x 8 Nonvolatile Static RAM

FEATURES

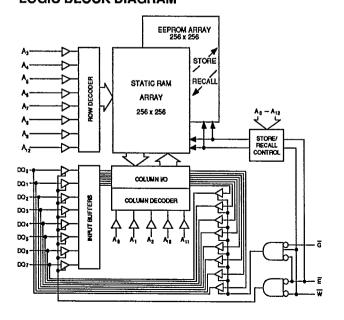
- 25, 30, 35 and 45ns Access Times
- 12, 15, 20 and 25ns Output Enable Access
- Unlimited Read and Write to SRAM
- Software STORE Initiation
- · Automatic STORE Timing
- 10⁴ or 10⁵ STORE cycles to EEPROM
- 10 year data retention in EEPROM
- Automatic RECALL on Power Up
- Software RECALL Initiation
- Unlimited RECALL cycles from EEPROM
- Single 5V±10% Operation
- · Commercial and Industrial Temperatures
- Available in multiple standard packages

DESCRIPTION

The Simtek STK11C68 is a fast static RAM (25, 30, 35, 45ns), with a nonvolatile electrically-erasable PROM (EEPROM) element incorporated in each static memory cell. The SRAM can be read and written an unlimited number of times, while independent nonvolatile data resides in EEPROM. Data transfers from the SRAM to the EEPROM (STORE), or from the EEPROM to the SRAM (RECALL) are initiated through software sequences. It combines the high performance and ease of use of a fast SRAM with nonvolatile data integrity.

The STK11C68 is pin compatible with industry standard SRAMs and is available in a 28-pin 300 mil plastic or ceramic DIP, and a 28-pin SOIC. MIL-STD-883 and Standard Military Drawing (SMD 5962-92324) devices are also available.

LOGIC BLOCK DIAGRAM



PIN CONFIGURATIONS

	∇	
NC 🛚 1	*•□ <u>v</u> ∞	
A 12 🖸 2	27 🗖 🗑	
٨٦Q3	#. □ NC	
٨.04	25 🗆 A 🛊	
A 5 🗆 8	*□ ∧*	
A4E *	23 🗀 A 11	
A 3 🗆 7	21 D A 12 21 D A 12	
۰ ۵٫۸	21 D A 12	
A, [] •	× D €	
A . [10	19 🗖 🖸 00 7	
DO . [] 11	11 DO 6	
DO , D 12	175 00 5	
DQ , [] 13	16 004	
VSS [] 14	15 🖰 100 s	
20 4	350 SOIC	
	300 PDIP	

PIN NAMES

A ₀ - A ₁₂	Address inputs
W	Write Enable
DQ ₀ - DQ ₇	Data In/Out
E	Chip Enable
Ğ	Output Enable
V _{CC}	Power (+5V)
V _{SS}	Ground

ABSOLUTE MAXIMUM RATINGS^a

Voltage on typical input relative to Vss. -0.6V to 7.0V Voltage on DQ₀₋₇ and G.....-0.5V to (V_{CC}+0.5V) Storage temperature.....-65°C to 150°C Power dissipation.....1W DC output current15mA Note a: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

(One output at a time, one second duration)

DC CHARACTERISTICS

 $(V_{CC} = 5.0V \pm 10\%)$

		СОММ	ERCIAL	INDUS	TRIAL		NOTES
SYMBOL	PARAMETER	MIN	MAX	Min	MAX	UNITS	NOTES
l _{CC1} b	Average V _{CC} Current		85		95	mA	t _{AVAV} = 25ns
•••			80		85	mA	t _{AVAV} = 30ns
			75		. 80	mA	t _{AVAV} = 35ns
		1	65		75	mA	t _{AVAV} = 45ns
lcc2d	Average V _{CC} Current		50		50	mA	E ≥ (V _{CC} - 0.2V)
	during STORE cycle						all others $V_{IN} \le 0.2V$ or $\ge (V_{CC} - 0.2V)$
I _{SB1} °	Average V _{CC} Current		30		34	mA	t _{AVAV} = 25ns
	(Standby, Cycling TTL Input Levels)		27		30	mA	t _{AVAV} = 30ns
			23		27	mA	t _{AVAV} = 35ns
			20		23	mA	t _{AVAV} = 45ns
							E ≥ V _{IH} ; all others cycling
I _{SB2} c	Average V _{CC} Current		1		1	mΑ	E ≥ (V _{CC} - 0.2V)
	(Standby, Stable CMOS Input Levels)						all others $V_{IN} \le 0.2V$ or $\ge (V_{CC} - 0.2V)$
I _{ILK}	Input Leakage Current (Any Input)		±1		±1	μА	V _{CC} = max
							V _{IN} = V _{SS} to V _{CC}
IOLK	Off State Output Leakage Current		±5		±5	μA	V _{CC} = max
							V _{IN} = V _{SS} to V _{CC}
V _{IH}	Input Logic "1" Voltage	2.2	V _{CC} +.5	2.2	V _{CC} +.5	٧	Ali Inputs
V _{IL}	Input Logic "0" Voltage	V _{SS} 5	0.8	V _{SS} 5	0.8	V	All Inputs
V _{OH}	Output Logic "1" Voltage	2.4		2.4		٧	l _{OUT} = –4mA
V _{OL}	Output Logic "0" Voltage		0.4		0.4	٧	l _{OUT} ≠ 8mA
TA	Operating Temperature	0	70	-40	85	ç	

Note b: ICC1 is dependent on output loading and cycle rate. The specified values are obtained with outputs unloaded.

Note c: Bringing E ≥ V_{IH} will not produce standby current levels until any nonvolatile cycle in progress has timed out. See MODE SELECTION table.

Note d: ICC2 is the average current required for the duration of the store cycle (ISTORE) after the sequence (IWC) that initiates the cycle.

AC TEST CONDITIONS

Input Pulse Levels	to 3V
Input Rise and Fall Times	≤5ns
Input and Output Timing Reference Levels	. 1.5V
Output Load See Fig	gure 1

CAPACITANCE (T_A=25°C, f=1.0MHz)^e

SYMBOL	PARAMETER	MAX	UNITS	CONDITIONS
CiN	Input Capacitance	5	₽F	ΔV = 0 to 3V
C _{OUT}	Output Capacitance	7	ρF	ΔV = 0 to 3V

Note e: These parameters are guaranteed but not tested.

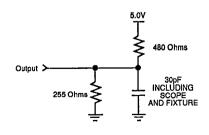


Figure 1: AC Output Loading

STK11C68

READ CYCLES #1 & #2

 $(V_{CC} = 5.0V \pm 10\%)$

	SYMBOLS			STK11	C68-25	STK11	C68-30	STK11	C68-35	STK11	C68-45	
NO.	#1, #2	Alt	PARAMETER	MIN	MAX	MIN	MAX	MEN	MAX	MIN	MAX	UNITS
1	t _{ELOV}	t _{ACS}	Chip Enable Access Time		25		30		35		45	ns
2	t _{AVAVR} g	t _{RC}	Read Cycle Time	25		30		35		45		ns
3	t _{AVQV} h	† _{AA}	Address Access Time		25		30		35		45	ns
4	t _{GLOV}	t _{OE}	Output Enable to Data Valid		12		15		20		25	ns
5	t _{AXQX}	t _{OH}	Output Hold After Address Change	5		5		5		5		ns
6	t _{ELOX}	t _{LZ}	Chip Enable to Output Active	5		5		5		5		ns
7	t _{EHOZ} I	t _{HZ}	Chip Disable to Output Inactive		13		15		17		20	ns
8	t _{GLOX}	toLZ	Output Enable to Output Active	0		0		0		0		ns
9	t _{GHOZ} i	t _{oHZ}	Output Disable to Output Inactive		13		15		17	_	20	ns
10	t _{ELICCH} •	t _{PA}	Chip Enable to Power Active	0		0		0		0		ns
11	t _{EHICCL} c.●	t _{PS}	Chip Disable to Power Standby		25		25		25		25	ns
11A	twHQV	t _{wa}	Write Recovery Time		30		35		45		55	ns

Note c: Bringing E≥ high will not produce standby currents until any nonvolatile cycle in progress has timed out. See MODE SELECTION table,

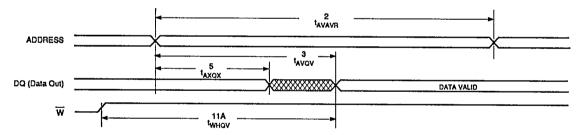
Note e: Parameter guaranteed but not tested.

Note g: For READ CYCLE #1 and #2, W must be high for entire cycle.

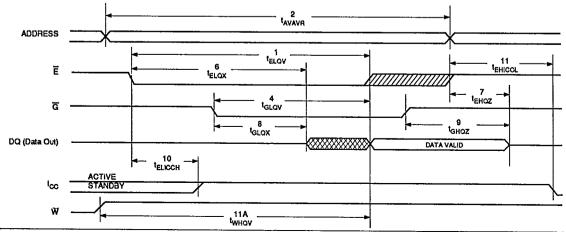
Note h: Device is continuously selected with \vec{E} low and \vec{G} low.

Note i: Measured ± 200mV from steady state output voltage.

READ CYCLE #1 g,h



READ CYCLE #2 g



3-11

SIMTEK CORP

68E D ■ 8274887 0000387 42T ■ SIK

STK11C68 _

WRITE CYCLES #1 & #2; G high (this table is effective 3/31/94)

 $(V_{CC} = 5.0V \pm 10\%)$

[SYMBOLS				STK11	C68-25	STK11	C68-30	STK11	C68-35	STK11	C68-45	UNITE
NO.	#1	#2	Alt	PARAMETER	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
12	† _{AVAVW}	† _{AVAVW}	twc	Write Cycle Time	25		30		35		45		ns
13	tww	†wleh	t _{WP}	Write Pulse Width	20		25		30		35		ПB
14	t _{ELWH}	t _{ELEH}	tcw	Chip Enable to End of Write	20		25		30		35		ns
15	t _{DVWH}	t _{DVEH}	t _{DW}	Data Set-up to End of Write	12		15		18		20		ns
16	twnpx	teHDX	t _{DH}	Data Hold After End of Write	0		0		0		0		ns
17	tavwh	taven	t _{AW}	Address Set-up to End of Write	20		25		30		35		ns
18	†AVWL	† _{AVEL}	tas	Address Set-up to Start of Write	0		0		0		0		ns
19	^t whax	tEHAX	twR	Address Hold After End of Write	0		0		0		0		ns

WRITE CYCLES #1 & #2; G low

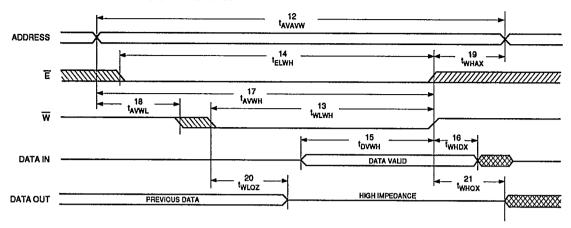
 $(V_{CC} = 5.0V \pm 10\%)$

	SYMBOLS				STK11	C68-25	STK11	C68-30	STK11	C68-35	STK11	C68-45	
NO.	#1	#2	Alt	PARAMETER	MIN	MAX	MIN	MAX	Min	MAX	MIN	MAX	UNITS
12	tavavw	tavavw	twc	Write Cycle Time	45		45		45		45		ns
13	tww	†WLEH	t _{WP}	Write Pulse Width	35		35		35		35		ns
14	tELWH	t _{ELEH}	tcw	Chip Enable to End of Write	35		35		35		35		ns
15	t _{DVWH}	toven	1 _{DW}	Data Set-up to End of Write	30		30		30		30		ns
16	twnpx	t _{EHDX}	t _{DH}	Data Hold After End of Write	0		0		0		0		ns
17	^t AVWH	^t AVEH	1 _{AW}	Address Set-up to End of Write	35		35		35		35		ns
18	t _{AVWL}	† _{AVEL}	1 _{AS}	Address Set-up to Start of Write	0		0		0		0		ns
19	twhax	† _{EHAX}	twn	Address Hold After End of Write	0		0		0		0		ns
20	tw.cozi,m		twz	Write Enable to Output Disable		35		35		35		35	ns
21	t _{wHOX}		tow	Output Active After End of Write	5		5		5		5		ns

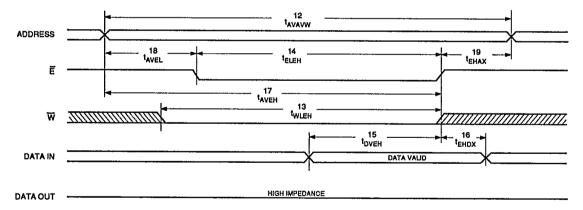
Note i: Measured \pm 200mV from steady state output voltage. Note k: \overline{E} or \overline{W} must be \geq V_{IH} during address transitions.

Note m: If \overline{W} is low when \overline{E} goes low, the outputs remain in the high impedance state.

WRITE CYCLE #1: W CONTROLLED k



WRITE CYCLE #2: E CONTROLLED k



STK11C68 _

NONVOLATILE MEMORY OPERATION

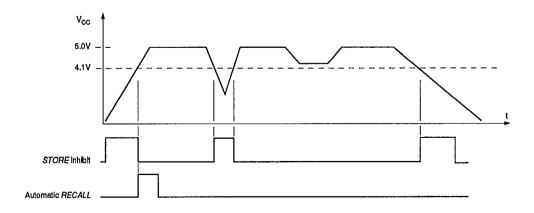
MODE SELECTION

Ē	W	A ₁₂ - A ₀ (hex)	MODE	I/O	POWER	NOTES
Н	X	Х	Not Selected	Output High Z	Standby	
L	Н	X	Read SRAM	Output Data	Active	0
L	L	Х	Write SRAM	Input Data	Active	
L	Н	0000	Read SRAM	Output Data	Active	n,o
		1555	Read SRAM	Output Data		n,o
		OAAA	Read SRAM	Output Data		n,o
		1FFF	Read SRAM	Output Data		n,o
		10F0	Read SRAM	Output Data		n,o
		OFOF	Nonvolatile STORE	Output High Z	l _{CC2}	n
L	Н	0000	Read SRAM	Output Data	Active	n,o
		1555	Read SRAM	Output Data		n,o
		OAAA	Read SRAM	Output Data		n,o
		1FFF	Read SRAM	Output Data		n,o
		10F0	Read SRAM	Output Data		n,o
		0F0E	Nonvolatile RECALL	Output High Z		n

Note n: The six consecutive addresses must be in order listed - (0000, 1555, 0AAA, 1FFF, 10F0, 0F0F) for a STORE cycle or (0000, 1555, 0AAA, 1FFF, 10F0, 0F0E) for a RECALL cycle. We must be high during all six consecutive cycles. See STORE cycle and RECALL cycle tables and diagrams for further details.

Note o: VO state assumes that $\overline{G} \le V_{IL}$. Initiation and operation of nonvolatile cycles does not depend on the state of \overline{G} .

STORE CYCLE INHIBIT and AUTOMATIC POWER-UP RECALL



STK11C68

STORE/RECALL CYCLE

 $(V_{CC} = 5.0V \pm 10\%)$

	SYMBOLS			STK11C68-25		STK11C68-30		STK11C68-35		STK11C68-45]
NO.	#1	Alt.	PARAMETER	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
22	t _{avavn}	t _{RC}	STORE/RECALL Initiation Cycle Time	25		30		35		45		ns
23	t _{ELOZ} P		Chip Enable to Output Inactive		75		75		75		75	ns
24	t _{ELOXS}	t _{STORE} q	STORE Cycle Time		10		10		10		10	ms
25	†ELOXR	tRECALL	RECALL Cycle Time		20		20		20		20	μѕ
26	taveln*	t _{AE}	Address Set-up to Chip Enable	0		0		0		0		ns
27	telehne,t	t _{EP}	Chip Enable Pulse Width	15		20		25		35		ns
28	tehaxn*	t _{EA}	Chip Disable to Address Change	0		0		0		0		ns

Note p: Once the software STORE or RECALL cycle is initiated, it completes automatically, ignoring all inputs.

Note q: Note that STORE cycles (but not RECALLs) are aborted by Vcc < 4.1V (STORE inhibit).

Note r: A RECALL cycle is initiated automatically at power up when V_{CC} exceeds 4.5V. t_{RECALL} is measured from the point at which V_{CC} exceeds 4.5V.

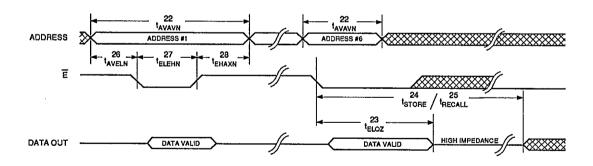
Note s: Noise on the \overline{E} pin may trigger multiple read cycles from the same address and abort the address sequence.

Note t: If the Chip Enable Pulse Width is less than teloy (see READ CYCLE #2) but greater than or equal to teleph, then the data may not be valid at the end of the low pulse, however the STORE or RECALL will still be initiated.

Note u: \overline{W} must be High when \overline{E} is Low during the address sequence in order to initiate a nonvolatile cycle. \overline{G} may be either High or Low throughout, Addresses #1 through #6 are found in the MODE SELECTION table. Address #6 determines whether the STK11C68 performs a STORE or RECALL.

Note v: E must be used to clock in the address sequence for the Software STORE and RECALL cycles.

STORE/RECALL CYCLE U,V



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DEVICE OPERATION

The STK11C68 has two separate modes of operation: SRAM mode and nonvolatile mode. In SRAM mode, the memory operates as an ordinary static RAM. In nonvolatile operation, data is transferred from SRAM to EEPROM or from EEPROM to SRAM. In this mode SRAM functions are disabled.

SRAM READ

The STK11C68 performs a READ cycle whenever \overline{E} and \overline{G} are LOW while \overline{W} is HIGH. The address specified on pins A_{0-12} determines which of the 8192 data bytes will be accessed. When the READ is initiated by an address transition, the outputs will be valid after a delay of t_{AVQV} (READ CYCLE #1). If the READ is initiated by \overline{E} or \overline{G} , the outputs will be valid at t_{ELQV} or at t_{GLQV} , whichever is later (READ CYCLE #2). The data outputs will repeatedly respond to address changes within the t_{AVQV} access time without the need for transitions on any control input pins, and will remain valid until another address change or until \overline{E} or \overline{G} is brought HIGH or \overline{W} is brought LOW.

SRAM WRITE

A write cycle is performed whenever \overline{E} and \overline{W} are LOW. The address inputs must be stable prior to entering the WRITE cycle and must remain stable until either \overline{E} or \overline{W} go HIGH at the end of the cycle. The data on pins DQ₀₋₇ will be written into the memory if it is valid t_{DVWH} before the end of a \overline{W} controlled WRITE or t_{DVEH} before the end of an \overline{E} controlled WRITE.

It is recommended that \overline{G} be kept HIGH during the entire WRITE cycle to avoid data bus contention on common I/O lines. If \overline{G} is left LOW, internal circuitry will turn off the output buffers t_{WLOZ} after \overline{W} goes LOW.

NONVOLATILE STORE

The STK11C68 STORE cycle is initiated by executing sequential READ cycles from six specific address locations. By relying on READ cycles only, the STK11C68 implements nonvolatile operation while remaining pin-for-pin compatible with standard 8Kx8 SRAMs. During the STORE cycle, an erase of the previous nonvolatile data is first performed, followed by a program of the nonvolatile elements. The program operation copies the SRAM data into nonvolatile elements. Once a STORE cycle is initiated, further input and output are disabled until the cycle is completed.

Because a sequence of reads from specific addresses is used for *STORE* initiation, it is important that no other read or write accesses intervene in the sequence or the sequence will be aborted and no *STORE* or

RECALL will take place.

To initiate the *STORE* cycle the following READ sequence must be performed:

4	D1-12	0000 /6-14	Valid READ
1.	Read address	0000 (hex)	
2.	Read address	1555 (hex)	Valid READ
3.	Read address	0AAA (hex)	Valid READ
4.	Read address	1FFF (hex)	Valid READ
5.	Read address	10F0 (hex)	Valid READ
6	Read address	OFOF (hex)	Initiate STORE Cycle

Once the sixth address in the sequence has been entered, the *STORE* cycle will commence and the chip will be disabled. It is important that READ cycles and not WRITE cycles be used in the sequence, although it is not necessary that \overline{G} be LOW for the sequence to be valid. After the t_{STORE} cycle time has been fulfilled, the SRAM will again be activated for READ and WRITE operation.

HARDWARE PROTECT

The STK11C68 offers hardware protection against inadvertent *STORE* cycles through $V_{\rm CC}$ Sense. A *STORE* cycle will not be initiated, and one in progress will discontinue, if $V_{\rm CC}$ goes below 4.1V. 4.1V is a typical, characterized value.

NONVOLATILE RECALL

A RECALL cycle of the EEPROM data into the SRAM is initiated with a sequence of READ operations in a manner similar to the STORE initiation. To initiate the RECALL cycle the following sequence of READ operations must be performed:

1.	Read address	0000 (hex)	Valid READ
2.	Read address	1555 (hex)	Valid READ
3.	Read address	OAAA (hex)	Valid READ
4.	Read address	1FFF (hex)	Valid READ
5.	Read address	10F0 (hex)	Valid READ
6.	Read address	0F0E (hex)	Initiate RECALL Cycle

Internally, RECALL is a two step procedure. First, the SRAM data is cleared and second, the nonvolatile information is transferred into the SRAM cells. The RECALL operation in no way alters the data in the EEPROM cells. The nonvolatile data can be recalled an unlimited number of times.

On power-up, once V_{CC} exceeds the V_{CC} Sense voltage of 4.1V, a *RECALL* cycle is automatically initiated. The voltage on the V_{CC} pin must not drop below 4.1V once it has risen above it in order for the *RECALL* to operate properly. Due to this automatic *RECALL*, SRAM operation cannot commence until t_{RECALL} after V_{CC} exceeds 4.1V. 4.1V is a typical, characterized value.

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ORDERING INFORMATION

